



74ABT126 Quad Buffer with 3-STATE Outputs

Features

- Non-inverting buffers
- Output sink capability of 64mA, source capability of 32mA
- Guaranteed latchup protection
- High impedance glitch free bus loading during entire power up and power down cycle
- Nondestructive hot insertion capability
- Disable time less than enable time to avoid bus contention

General Description

The ABT126 contains four independent non-inverting buffers with 3-STATE outputs.

Ordering Information

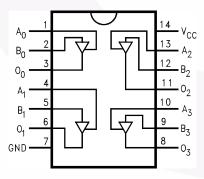
Order Number	Package Number	Package Description
74ABT126CSC	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74ABT126CSJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74ABT126CMTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.



All packages are lead free per JEDEC: J-STD-020B standard.

Connection Diagram



Pin Description

Pin Names	Description		
A _n , B _n	Inputs		
O _n	Outputs		

Function Table

Inp	uts	Output
An	B _n	O _n
Н	L	L
Н	Н	Н
L	Х	Z

H = HIGH Voltage Level

L = LOW Voltage Level

Z = HIGH Impedance

X = Immaterial

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
T _{STG}	Storage Temperature	−65°C to +150°C
T _A	Ambient Temperature Under Bias	–55°C to +125°C
T _J	Junction Temperature Under Bias	−55°C to +150°C
V _{CC}	V _{CC} Pin Potential to Ground Pin	-0.5V to +7.0V
V _{IN}	Input Voltage ⁽¹⁾	-0.5V to +7.0V
I _{IN}	Input Current ⁽¹⁾	-30mA to +5.0mA
V _O	Voltage Applied to Any Output	
	Disabled or Power-Off State	-0.5V to 5.5V
	HIGH State	–0.5V to V _{CC}
	Current Applied to Output in LOW State (Max.)	twice the rated I _{OL} (mA)
	DC Latchup Source Current (Across Comm Operating Range)	-300mA
	Over Voltage Latchup (I/O)	10V

Note:

1. Either voltage limit or current limit is sufficient to protect inputs.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
T _A	Free Air Ambient Temperature	-40°C to +85°C
V _{CC}	Supply Voltage	+4.5V to +5.5V
ΔV / Δt	Minimum Input Edge Rate	
	Data Input	
	Enable Input	100mV/ns

DC Electrical Characteristics

Symbol	Parameter		V _{CC}	Conditions	Min.	Тур.	Max.	Units
V _{IH}	Input HIGH Voltage			Recognized HIGH Signal	2.0			V
V _{IL}	Input LOW Voltage			Recognized LOW Signal			0.8	V
V _{CD}	Input Clam	o Diode Voltage	Min.	I _{IN} = -18mA			-1.2	V
V _{OH}	Output HIG	H Voltage	Min.	$I_{OH} = -3mA$	2.5			V
				$I_{OH} = -32mA$	2.0			
V_{OL}	Output LOV	V Voltage	Min.	I _{OL} = 64mA			0.55	V
I _{IH}	Input HIGH	Current	Max.	$V_{IN} = 2.7V^{(2)}$			1	μA
				$V_{IN} = V_{CC}$			1	
I _{BVI}	Input HIGH Test	Current Breakdown	Max.	V _{IN} = 7.0V			7	μA
I _{IL}	Input LOW	Current	Max.	$V_{IN} = 0.5V^{(2)}$			-1	μA
				$V_{IN} = 0.0V$			-1	1
V _{ID}	Input Leakage Test		0.0	I _{ID} = 1.9μA, All Other Pins Grounded	4.75			V
I _{OZH}	Output Leakage Current		0-5.5V	$V_{OUT} = 2.7V, \overline{OE}_n = 2.0V$			10	μΑ
I _{OZL}	Output Leakage Current		0-5.5V	$V_{OUT} = 0.5V, \overline{OE}_n = 2.0V$			-10	μA
Ios	Output Short-Circuit Current		Max.	$V_{OUT} = 0.0V$	-100		-275	mA
I _{CEX}	Output HIG	H Leakage Current	Max.	$V_{OUT} = V_{CC}$			50	μA
I _{ZZ}	Bus Draina	ge Test	0.0	V _{OUT} = 5.5V, All Others GND			100	μΑ
I _{CCH}	Power Sup	oly Current	Max.	All Outputs HIGH			50	μΑ
I _{CCL}	Power Sup	oly Current	Max.	All Outputs LOW			15	mA
I _{CCZ}	Power Supply Current		Max.	$\overline{OE}_n = V_{CC}$, All Others at V_{CC} or Ground			50	μA
I _{CCT}	Additional Outputs Enabled		Max.	$V_I = V_{CC} - 2.1V$			1.5	mA
	I _{CC} /Input	Outputs 3-STATE		Enable Input V _I = V _{CC} - 2.1V			1.5	mA
	Outputs 3-STATE			Data Input $V_I = V_{CC} - 2.1V$, All Others at V_{CC} or Ground			50	μA
I _{CCD}	Dynamic I _{CC} No Load ⁽²⁾		Max.	Outputs OPEN, $\overline{OE}_n = GND^{(3)}$, One-Bit Toggling, 50% Duty Cycle			0.1	mA/ MHz

Notes:

- 2. Guaranteed, but not tested.
- 3. For 8-bit toggling, $I_{CCD} < 0.8 mA/MHz$.

AC Electrical Characteristics

		T _A = +25°C, V _{CC} = +5V, C _L = 50pF		C, V, F	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $V_{CC} = 4.5\text{V} -5.5\text{V}$ $C_L = 50\text{pF}$		
Symbol	Parameter	Min.	Тур.	Max.	Min.	Max.	Units
t _{PLH}	Propagation Delay, Data to Outputs	1.0		4.4	1.0	4.4	ns
t _{PHL}		1.0		4.6	1.0	4.6	
t _{PZH}	Output Enable Time	1.0		6.5	1.0	6.5	ns
t _{PZL}		1.0		6.5	1.0	6.5	
t _{PHZ}	Output Disable Time	1.0		5.8	1.0	5.8	ns
t _{PLZ}		1.0		5.5	1.0	5.5	

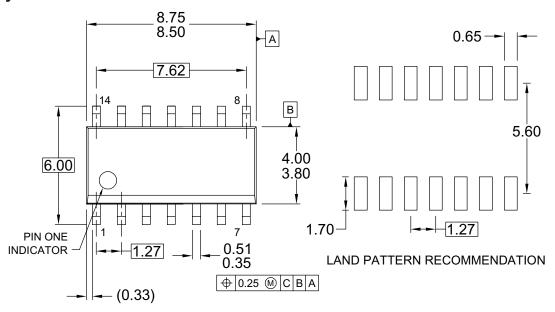
Capacitance

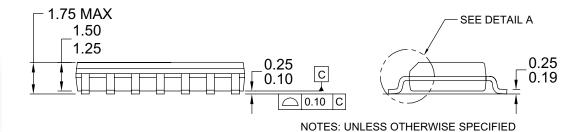
Symbol	Parameter	Conditions T _A = 25°C	Тур.	Units
C _{IN}	Input Capacitance	$V_{CC} = 0V$	5.0	pF
C _{OUT} ⁽⁴⁾	Output Capacitance	$V_{CC} = 5.0V$	9.0	pF

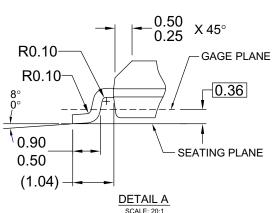
Note:

4. C_{OUT} is measured at frequency f = 1MHz, per MIL-STD-883, Method 3012.

Physical Dimensions







- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C,
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X145-14M
- E) DRAWING CONFORMS TO ASME Y14.5M-1994
- F) DRAWING FILE NAME: M14AREV13

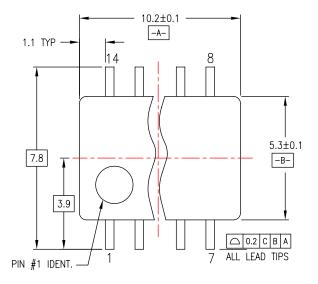
Figure 1. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow

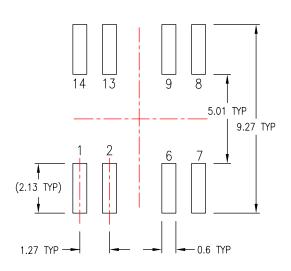
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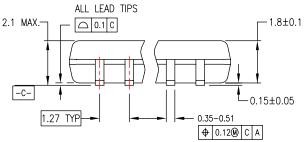
http://www.fairchildsemi.com/packaging/

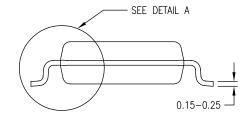
Physical Dimensions (Continued)





LAND PATTERN RECOMMENDATION



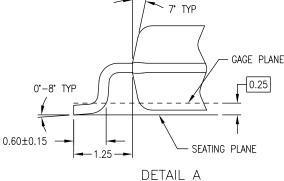


DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
 B. DIMENSIONS ARE IN MILLIMETERS.
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD

FLASH, AND TIE BAR EXTRUSIONS.



M14DREVC

Figure 2. 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

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Physical Dimensions (Continued) 5.0±0.1 -A-0.65 0.43 TYP 6.4 4.4±0.1 -B-1.65 3.2 □ 0.2 C B A PIN #1 IDENT. 6.10 0.45 -LAND PATTERN RECOMMENDATION SEE DETAIL A ALL LEAD TIPS 0.90+0.15 1.2 MAX □ 0.1 C 0.09-0.20 -C-0.10±0.05 0.65 0.19 - 0.30⊕ |0.13\\(\) |A |B\(\) |C\(\) 12.00°TOP & BOTTOM R0.09 min GAGE PLANE 0.25 0°-8° NOTES: 0.6±0.1 A. CONFORMS TO JEDEC REGISTRATION MO-153, SEATING PLANE R0.09min VARIATION AB, REF NOTE 6 -1 00 **B. DIMENSIONS ARE IN MILLIMETERS DETAIL A**

- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH,
- AND TIE BAR EXTRUSIONS D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982
- E. LANDPATTERN STANDARD: SOP65P640X110-14M
- F. DRAWING FILE NAME: MTC14REV6

Figure 3. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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